| ASSOCIATION CONNECTING LECTRONICS INDUSTRIES® INCLUSTRIES® | C. Bannockł | ourn. Illinois. A | ll rights reserved unitions. | under both | This docume level parts, t | ent is a declara he declaration | tion of the s encompasse | ubstances es all lowe | within the n r level mater | nanufacture rials for wh | r listed item ich the manu | Note: if | the item is an as has engineering | sembly with lowe responsibility. |
|---|--|-----------------------------|------------------------------|---------------|---|------------------------------------|---|--------------------------|-------------------------------|---------------------------------|-------------------------------|------------------|-----------------------------------|-------------------------------------|
| | IPC Web Site for Information on IPC-1752 Standard Form http://www.ipc.org/IPC-175x Distribution | | | | * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi | | | | | ous Materia | als and Mfg Information | | | |
| Supplier Information | | | | | | | | | | | | | | |
| Company name* Comp | | | Company unique ID | | | Unique ID Authority | | | | | Response Date* | | | |
| onsemi | semi | | | | | | | | | | 2024-05-11 | | | |
| Contact Name | t Name Title - Contact | | | | | Phone - Contact* | | | | | Email - Contact* | | | |
| Product-Env-Stewards Product Envi | | | iro Compliance | | | NA | | | | Product-Env-Stewards@onsemi.com | | | | |
| Authorized Representative* Title - Represen | | | entative | | | Phone - Representative* | | | | Email - Representative* | | | | |
| Product-Env-Stewards Pr | | | Product Enviro Compliance | | | NA | | | | Product-Env-Stewards@onsemi.com | | | | |
| Requester Item Number | Mfr Item | n Number | Mfr Item Name | | | Effective Dat | e Version | | Manufacturing Site | | Wei | ght* | UOM | Unit Type |
| | NTMFS: | MFS5C442NLT1G NFET SO8FL 40 | | V 126A 2.8MO | | 2024-05-11 | | | MY1 | | 100 | 77 | mg | Each |
| Manufacturing Proccess Informat | ion | | - | | | | | | | | | | | |
| Terminal Plating / Grid Array Ma | erial Terminal Base Alloy | | Alloy | J-STD-020 MSI | L Rating | Peak Pro | k Process Body Temperature Max Time at Peal | | ne at Peak T | Temperature Number of | | er of Reflow Cyc | les | |
| Matte Tin (Sn) - annealed CU Alloy | | | 1 | | 260 | | С | 30 | | seconds | 3 | | | |
| Comments | | | | | | | | | | | | | | |
| evel 1 - maximum time at peak temperatu | re during so | ldering is 10-3 | 0 seconds | | | | | | | | | | | |
| for more information regarding material | composition | please refer to | page 3 | | | | | | | | | | | |

| RoHS Material Composition Declaration | | | | Declaration Type * | Detailed | | | | | | |
|--|--|--|---|---|---|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS Directive 2011/65/EU | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP). | | | | | | | | | | |
| cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company | ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the | henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg | nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co | e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica | ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of | | | | | | |
| RoHS Declaration * 4 - Item(| s) does not contain RoHS restricted subst | ances per the definition above except for sele | ected exempt | ions Supplier Acceptance | * Accepted | | | | | | |
| Exemption: 7a: Lead in high melting temp | erature type solders (i.e. lead based sol | der alloys containing 85% by weight or m | ore lead). | | | | | | | | |
| Exemption List Version | EL-2011/534/EU | | | | | | | | | | |
| Declaration Signature | | | | | | | | | | | |
| Instructions: Complete all of the required Requester) and click on Submit Form to h | | | e drop-dowi | a. This will display the signature area. Digita | lly sign the declaration (if required by the | | | | | | |
| Supplier Digital Signature | astislav Drska | Le | | | | | | | | | |

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level | Substance | CAS | Exempt | Weight | Unit of Measure |
|----------------------|--------|-----------------|----------|-------------------------|------------------|--------|---------|-----------------|
| Clip | 4.8 | mg | Supplier | Zinc (Zn) | 7440-66-6 | | 0.0058 | mg |
| | | | Supplier | Iron (Fe) | 7439-89-6 | | 0.1128 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 4.68 | mg |
| | | | Supplier | Phosphorus (P) | 7723-14-0 | | 0.0014 | mg |
| Die | 2.0 | mg | Supplier | Silicon (Si) | 7440-21-3 | | 2 | mg |
| Die Attach Solder | 2.33 | mg | Supplier | Silver (Ag) | 7440-22-4 | | 0.0582 | mg |
| | | | А | Lead (Pb) | 7439-92-1 | 7a | 2.1553 | mg |
| | | | Supplier | Tin (Sn) | 7440-31-5 | | 0.1165 | mg |
| Lead Frame | 47.6 | mg | Supplier | Silver (Ag) | 7440-22-4 | | 0.0048 | mg |
| | | | Supplier | Zinc (Zn) | 7440-66-6 | | 0.0952 | mg |
| | | | Supplier | Iron (Fe) | 7439-89-6 | | 1.2371 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 46.1915 | mg |
| | | | Supplier | Phosphorus (P) | 7723-14-0 | | 0.0714 | mg |
| Mold Compound-Black | 42.24 | mg | | Epoxy resin | proprietary data | | 3.168 | mg |
| | | | Supplier | Phenolic Resin | Proprietary Data | | 1.056 | mg |
| | | | Supplier | Silica Amorphous (SiO2) | 7631-86-9 | | 3.168 | mg |
| | | | Supplier | Carbon Black (C) | 1333-86-4 | | 0.2112 | mg |
| | | | Supplier | Fused Silica (SiO2) | 60676-86-0 | | 34.6368 | mg |
| Plating | 1.7 | mg | Supplier | Tin (Sn) | 7440-31-5 | | 1.7 | mg |
| Wire Bond - Cu | 0.1 | mg | Supplier | Copper (Cu) | 7440-50-8 | | 0.1 | mg |

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).